

Robin Cheung, et al.

Group Art Unit: 1741

**Examiner:** Erica Smith Hicks

RECEIVED  
MAR 11 2003  
TC 1700 MAIL ROOM

**For: Apparatus For Electro  
Chemical Deposition Of  
Copper metallization With  
The Capability Of In-Situ  
Thermal Annealing**

**CERTIFICATE OF MAILING**  
37 CFR 1.8

I hereby certify that this correspondence is being deposited on  
March 4, 2003 with the United States Postal Service as First  
Class Mail in an envelope addressed to: Commissioner for  
Patents, Washington, D.C. 20231.

March 4, 2003 \_\_\_\_\_  
Date Signature

**5  
RESPONSE TO OFFICE ACTION DATED DECEMBER 4, 2002**

03/12/2003 WHITCHEL 00000005 RESPONSE 141

01 FC:1202 234.00 CH

In response to the Office Action dated December 4, 2002, having a shortened statutory period for response set to expire on March 4, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. The Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/3421.C1/CMP/ECP/NAN, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**Please amend the claims as follows:**

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